

RF360 Europe GmbH

A Qualcomm – TDK Joint Venture

SAW Components

SAW Duplexer for femtocell

Band 13 (3G/LTE)

Series/type: B7939
Ordering code: B39781B7939P810

Date: June 17, 2015
Version: 2.1

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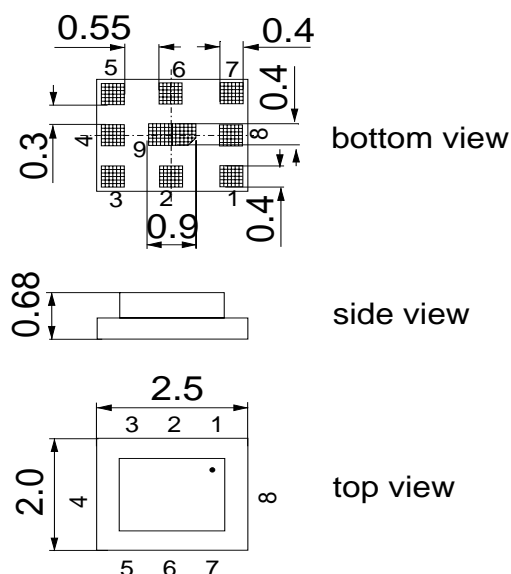
Datasheet


Application

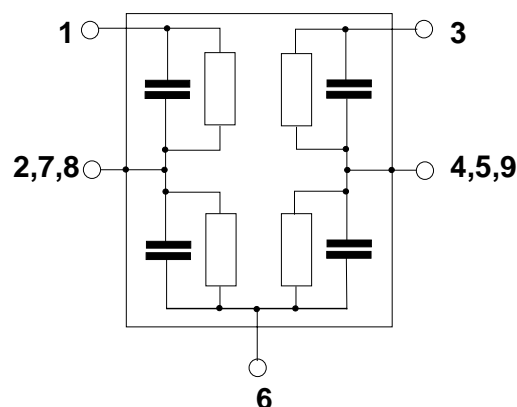
- Low-loss SAW duplexer for 3G/LTE femtocell systems (Band 13)
- Low insertion attenuation
- Low amplitude ripple
- Usable passband 10 MHz
- High power durability


Features

- Package size 2.5 * 2.0 * 0.68 mm³
- RoHS compatible
- Package for **Surface Mount Technology (SMT)**
- Ni, Au-plated terminals
- **Electrostatic Sensitive Device (ESD)**
- Moisture Sensitivity Level 3
- RX = UPLINK = 777-787 MHz
- TX = DOWNLINK = 746-756 MHz


Pin configuration

- 3 RX output
- 1 TX input
- 6 Antenna
- 2, 4, 5, 7, 8, 9 To be grounded



Datasheet

Characteristics

Temperature range for specification:	T = -10 °C to +85 °C
Antenna terminating impedance:	Z _{ANT} = 50 Ω 16 nH
RX terminating impedance:	Z _{RX} = 50 Ω
TX terminating impedance:	Z _{TX} = 50 Ω

Characteristics ANT - RX		B7939			
		min.	typ. @ 25 °C	max.	
Center frequency	f _C		782.0		MHz
Maximum insertion attenuation 777.0 ... 787.0 MHz	α _{max}	-	2.0	2.5	dB
Amplitude ripple (p-p) 777.0 ... 787.0 MHz	Δα	-	0.6	1.5	dB
Error Vector Magnitude @f _{carrier} 779.5 ... 784.5 MHz	EVM ¹⁾	-	1.8	3.0	%
Input VSWR (ANT port) 777.0 ... 787.0 MHz		-	1.5	1.8	
Output VSWR (RX port) 777.0 ... 787.0 MHz		-	1.5	1.8	
Attenuation	α				
10.0 ... 150.0 MHz		40	58	-	dB
150.0 ... 350.0 MHz		35	45	-	dB
350.0 ... 650.0 MHz		30	41	-	dB
728.0 ... 746.0 MHz		35	47	-	dB
746.0 ... 756.0 MHz		50	56	-	dB
758.0 ... 768.0 MHz		28	31	-	dB
808.0 ... 818.0 MHz		35	44	-	dB
859.0 ... 894.0 MHz		35	44	-	dB
1452.0 ... 1492.0 MHz		40	48	-	dB
1554.0 ... 1574.0 MHz		40	49	-	dB
1574.0 ... 1606.0 MHz		45	50	-	dB
1670.0 ... 1675.0 MHz		40	51	-	dB
1930.0 ... 1995.0 MHz		40	53	-	dB
2110.0 ... 2170.0 MHz		40	50	-	dB
2300.0 ... 2361.0 MHz		30	34	-	dB
2361.0 ... 2690.0 MHz		30	37	-	dB
3300.0 ... 3800.0 MHz		15	20	-	dB
5150.0 ... 5850.0 MHz		5	12	-	dB

1) Error Vector Magnitude (EVM) based on definition given in 3GPP TS 25.141

Datasheet

Characteristics

Temperature range for specification:	T = -10 °C to +85 °C
Antenna terminating impedance:	Z _{ANT} = 50 Ω 16 nH
RX terminating impedance:	Z _{RX} = 50 Ω
TX terminating impedance:	Z _{TX} = 50 Ω

Characteristics TX - ANT		B7939			
		min.	typ. @ 25 °C	max.	
Center frequency	f _C		751.0		MHz
Maximum insertion attenuation 746.0 ... 756.0 MHz	α _{max}	-	1.6	2.0	dB
Amplitude ripple (p-p) 746.0 ... 756.0 MHz	Δα	-	0.4	1.0	dB
Error Vector Magnitude @f _{carrier} 748.5 ... 753.5 MHz	EVM ¹⁾	-	1.4	2.5	%
Input VSWR (TX port) 746.0 ... 756.0 MHz		-	1.5	1.8	
Output VSWR (ANT port) 746.0 ... 756.0 MHz		-	1.4	1.8	
Attenuation	α				
10.0 ... 150.0 MHz		40	60	-	dB
150.0 ... 350.0 MHz		35	46	-	dB
350.0 ... 650.0 MHz		30	37	-	dB
698.0 ... 716.0 MHz		35	38	-	dB
716.0 ... 722.0 MHz		38	42	-	dB
777.0 ... 787.0 MHz		55	60	-	dB
788.0 ... 798.0 MHz		45	54	-	dB
798.0 ... 849.0 MHz		35	40	-	dB
1492.0 ... 1543.0 MHz		35	38	-	dB
1554.0 ... 1574.0 MHz		35	38	-	dB
1574.0 ... 1606.0 MHz		35	38	-	dB
1710.0 ... 1770.0 MHz		35	38	-	dB
1850.0 ... 1915.0 MHz		35	37	-	dB
1920.0 ... 1980.0 MHz		35	39	-	dB
2200.0 ... 2690.0 MHz		35	38	-	dB
2690.0 ... 3800.0 MHz		25	30	-	dB
5150.0 ... 5850.0 MHz		5	19	-	dB

1) Error Vector Magnitude (EVM) based on definition given in 3GPP TS 25.141

Datasheet

Characteristics

Temperature range for specification:	T = -10 °C to +85 °C
Antenna terminating impedance:	Z _{ANT} = 50 Ω 16 nH
RX terminating impedance:	Z _{RX} = 50 Ω
TX terminating impedance:	Z _{TX} = 50 Ω

Characteristics TX-RX				B7939				
				min.	typ. @ 25 °C	max.		
Attenuation	746.0 ... 756.0 MHz	...	756.0 MHz	α	50	55	-	dB
					52	59	-	dB

Maximum Ratings

Storage temperature range	T _{stg}	-40/+85	°C	
DC voltage	V _{DC}	0	V	
ESD voltage	V _{ESD}	50 ¹⁾	V	machine model, 10 pulses HBM model, 1 pulse
		250 ²⁾	V	
Input power at pin 1				source and load impedance 50 Ω
746.0 ...756.0 MHz	P _{in}	30.5	dBm	} average power T = 55°C, 50.000 h
elsewhere	P _{in}	10	dBm	

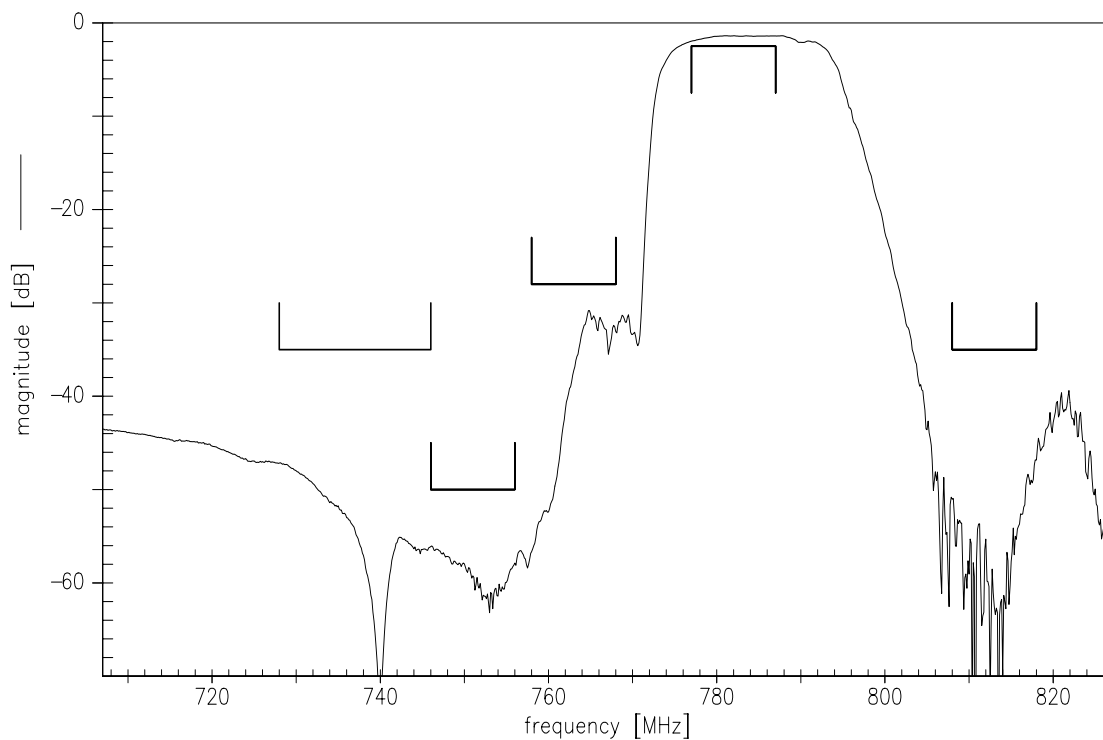
1) According to JESD22-A115A (machine model), 10 negative and 10 positive pulses.

2) According to JESD22-A114F (Human Body Model), +/-1 pulse.

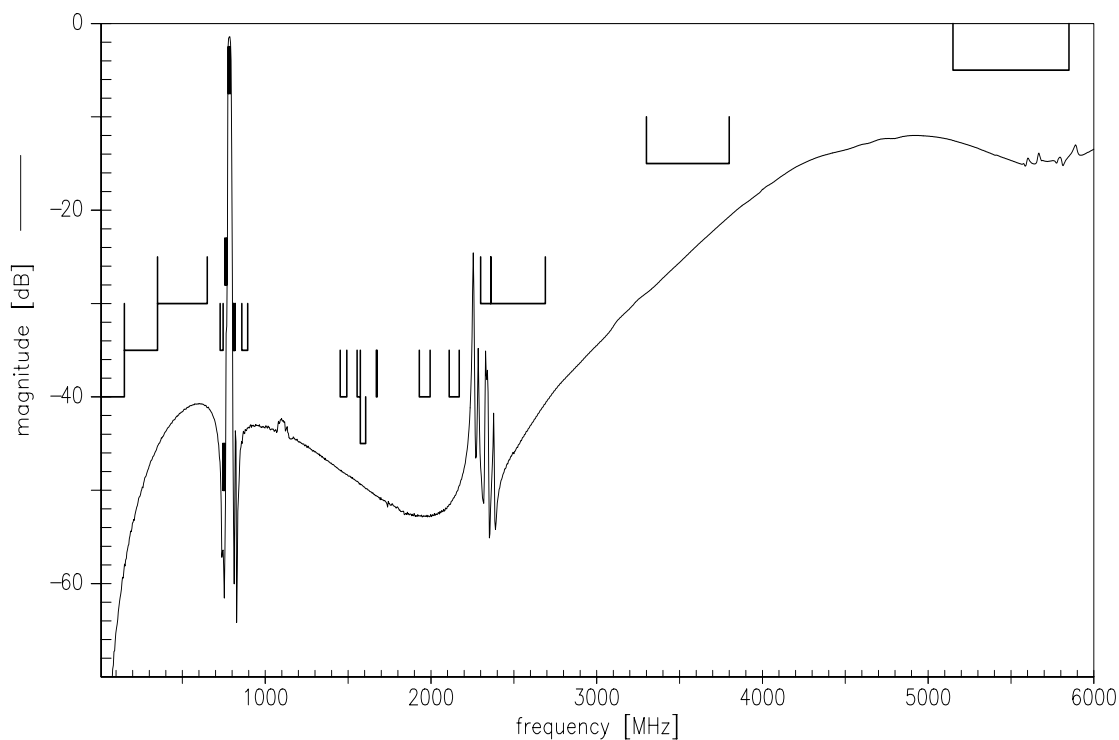
Datasheet



Frequency Response ANT-RX



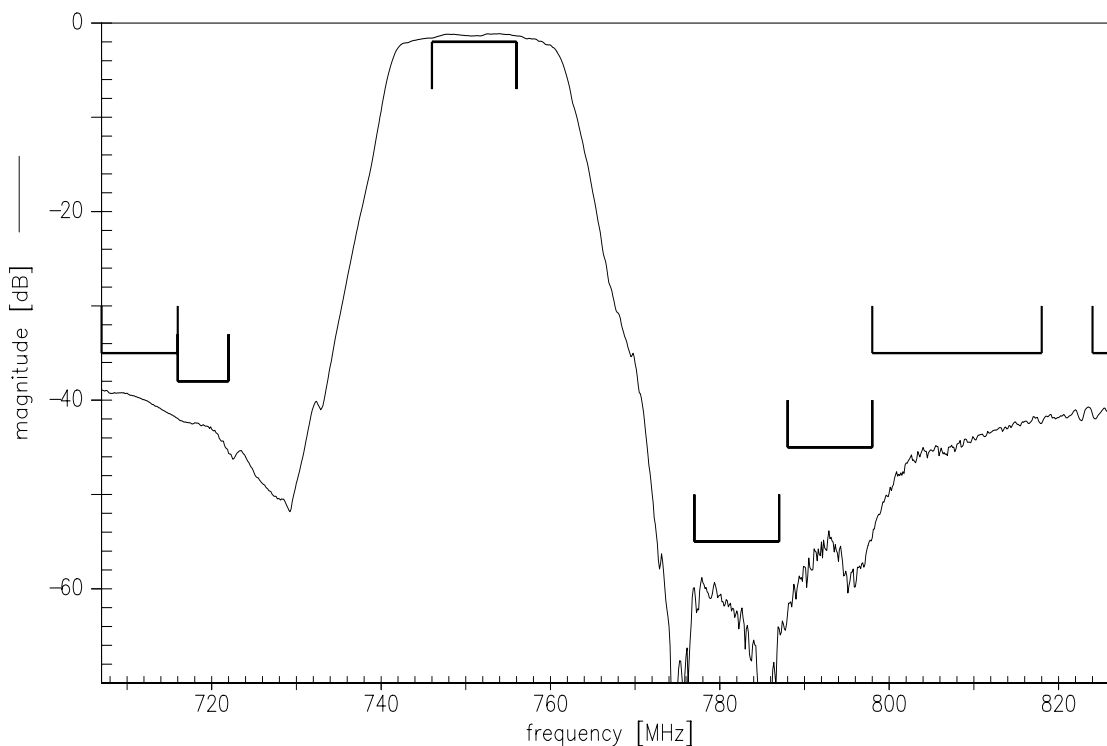
Frequency Response ANT-RX



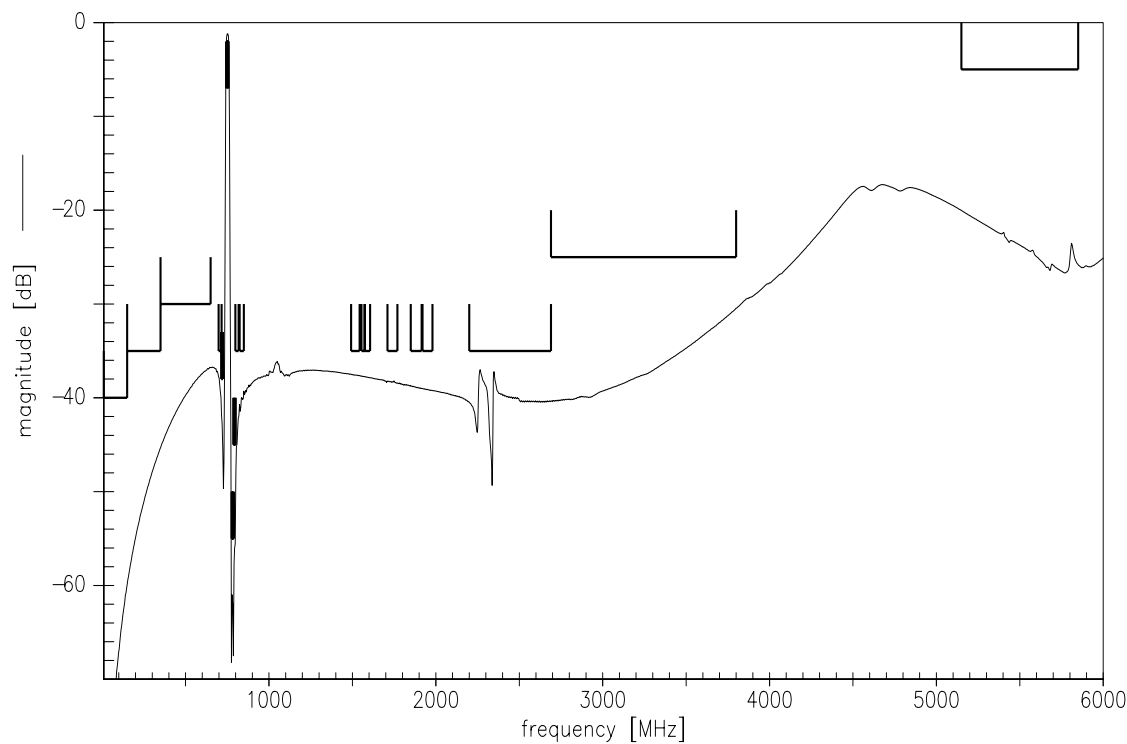
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Frequency Response TX-ANT



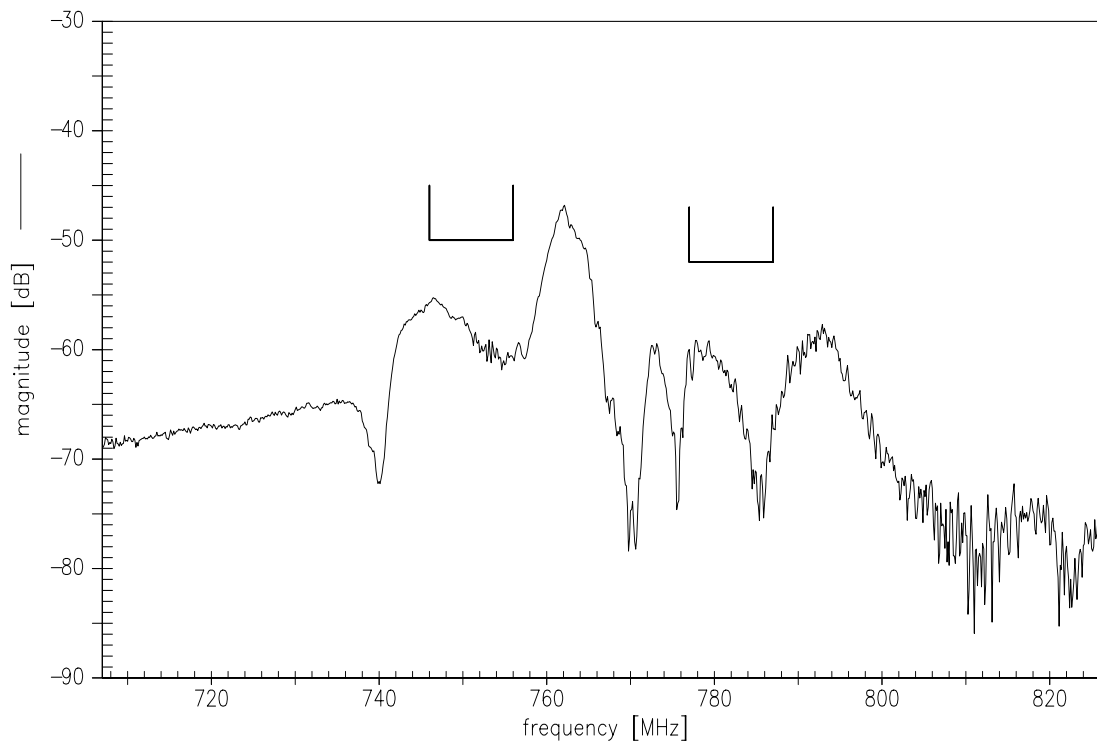
Frequency Response TX-ANT



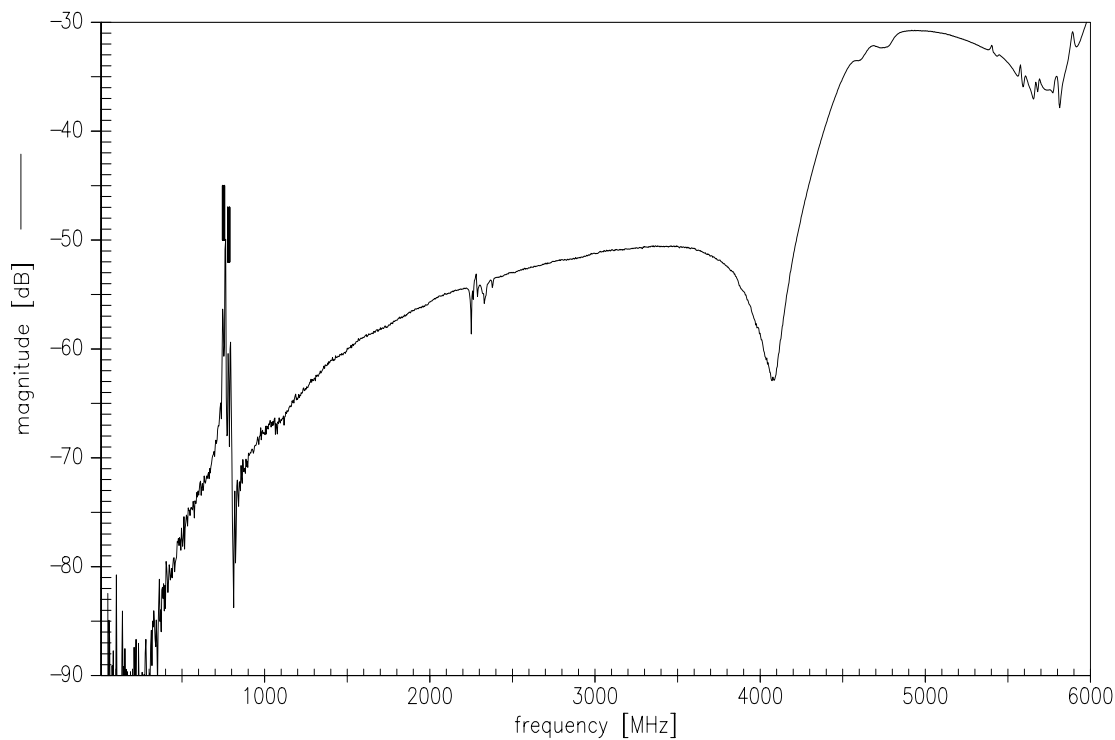
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Frequency Response RX-TX



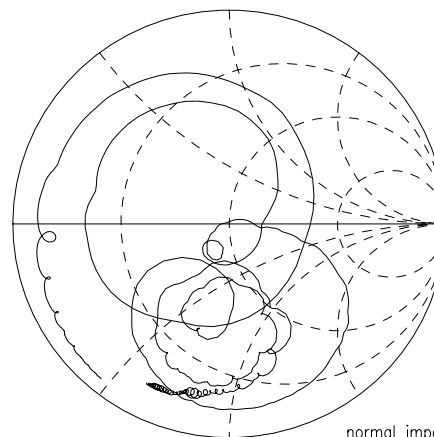
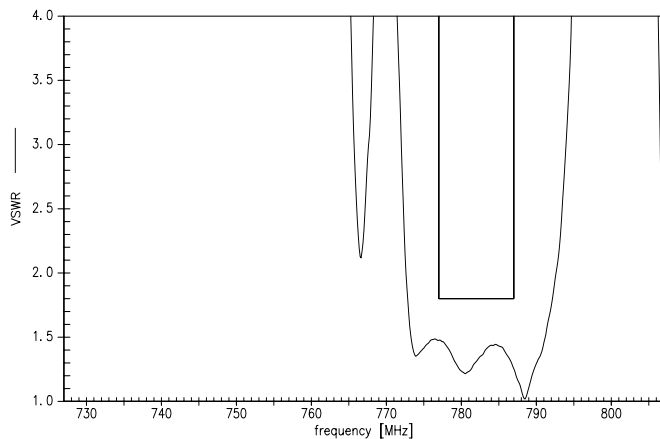
Frequency Response RX-TX



Datasheet

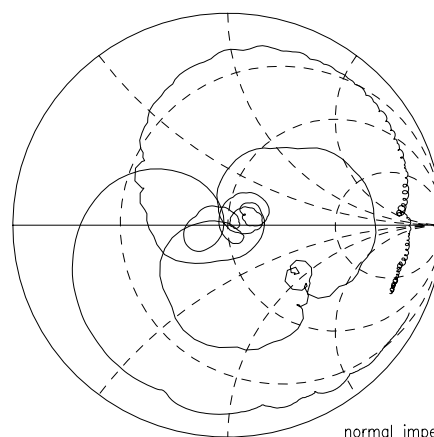
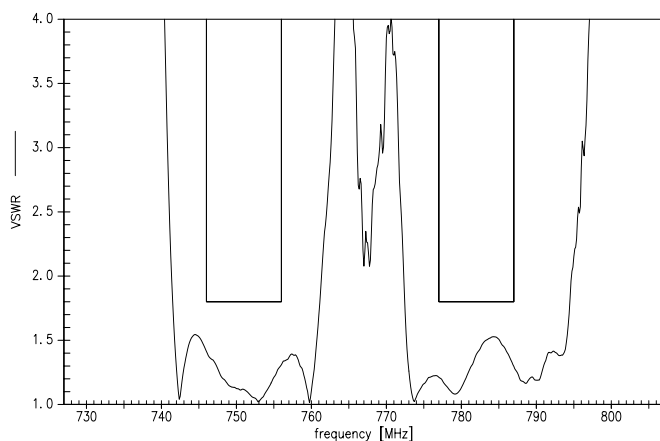


S11 VSWR (RX)



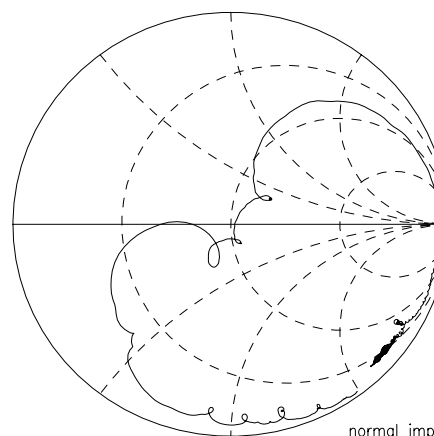
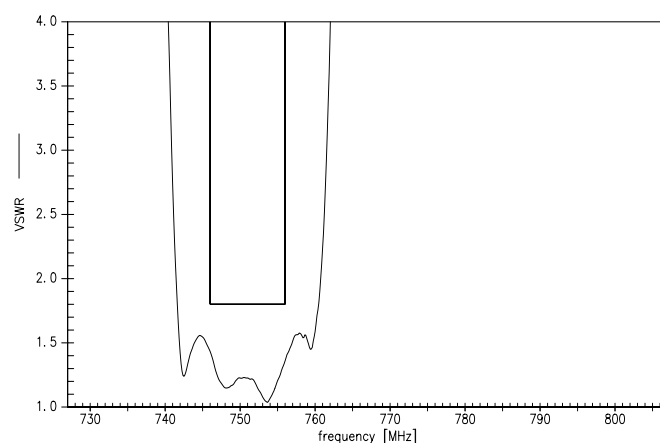
normal impedance: 50.00 Ω

S22 VSWR (ANT)



normal impedance: 50.00 Ω

S33 VSWR (TX)

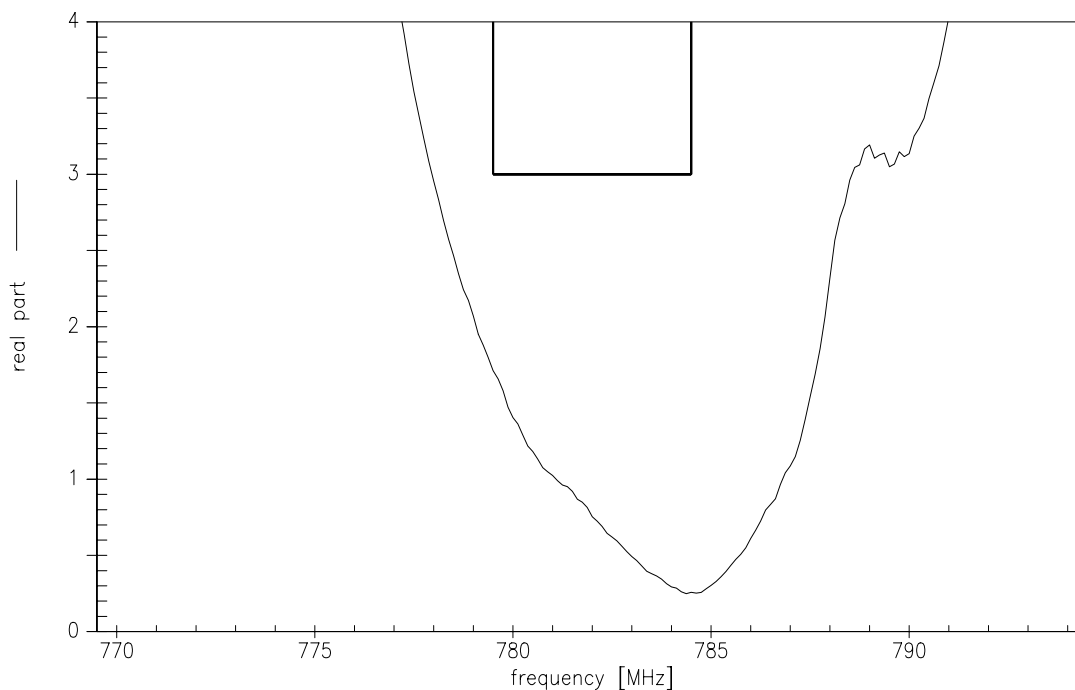


normal impedance: 50.00 Ω

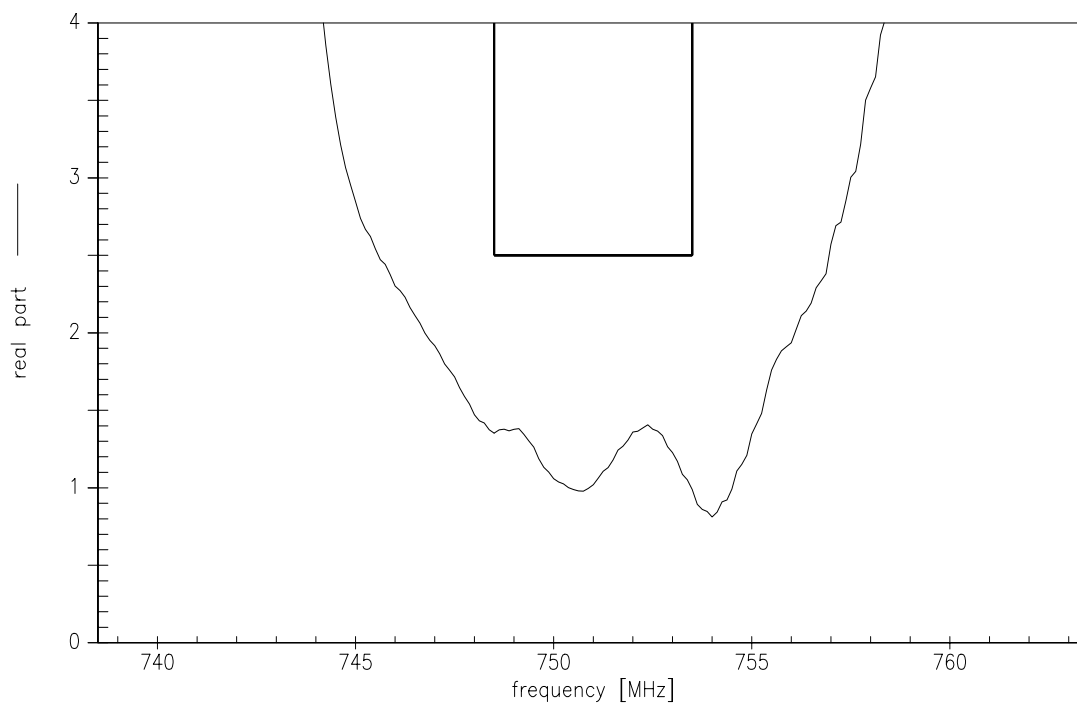
Datasheet



EVM RX



EVM TX



Datasheet



Reference

Type	B7939
Ordering code	B39781B7939P810
Marking and package	C61157-A3-A61
Packaging	F61074-V8153-Z000
Date codes	L_1126
S-parameters	B7939_NB.s3p, B7939_WB.s3p See file header for port/pin assignment table.
Soldering profile	S_6001
RoHS compatible	RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8 th , 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.
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